



**Monday June 5, 3:24 pm Eastern Time**  
**Company Press Release**

## **HCD Signs Rambus RIMM Module Partnership Agreement**

SUNNYVALE, Calif.--(BUSINESS WIRE)--June 5, 2000--High Connection Density (HCD), designer and manufacturer of high-performance PC boards and inventor of high-frequency, high-density connector technology, today announced it has signed a partnership agreement with Rambus Inc. (Nasdaq:RMBS - news) to provide high performance Rambus® RIMM(TM) modules. As a Rambus partner, HCD provides another source of high-quality RIMM modules to PC OEMs.

HCD leverages 30 years of electronic packaging experience to produce a line of Rambus products ranging from 64MB to 256MB RIMM modules. HCD's modules using 128Mb RDRAM® devices based on HCD's custom PCB design have passed Rambus' validation tests. By using their own PCB design, HCD expects to reduce cost and improve system robustness. HCD is also working on custom high density modules which will increase the amount of memory per module and will be key to addressing the needs of the server market. Designs are complete for next-generation RIMM modules using 256Mb RDRAMs following the same superior PCB design rules and process which are applied to HCD's 128Mb RDRAM based RIMM designs.

"HCD rapidly established manufacturing in Taiwan and was able to produce RIMM modules which passed the Rambus validation tests." said Laura Fleming, VP, Alliances and Infrastructure at Rambus Inc. "We are pleased that HCD has confidence in its ability to innovate beyond manufacturing standard RIMM modules and intends to independently create designs which expand the overall market for RDRAM "

"In addition to the PC and server markets, HCD will further accelerate the use of Rambus technology in new markets such as telecom and network communication routers. We do this by offering custom high-speed design services, world-class Asia and US manufacturing facilities and high-performance, dense interconnect technology to provide quick, turn-key solutions of custom form-factor, high-performance RIMM modules," said Dirk Brown, Ph.D., General Manager of the Module Business Unit at HCD.

HCD plans to expand its portfolio of RDRAM based modules by independently pursuing custom module design. HCD is presently developing a low profile, small footprint module geared toward very compact systems. A significant advantage of the HCD custom small footprint module is the ability to upgrade system memory without increasing the footprint used on the motherboard. The small module also includes an integrated, low cost thermal solution. The thermal solution is just one example of how HCD's broad experience base will allow it to provide tailored solutions which simplify the system design task.



HIGH CONNECTION DENSITY, INC.

[www.hcdcorp.com](http://www.hcdcorp.com)

## About High Connection Density, Inc.

High Connection Density, Inc. offers high-speed PCB design, verification and world-class manufacturing services providing quick, turn-key solutions to the high-end computer, consumer electronics and communication industry worldwide. HCD products include a family of standard and custom Rambus memory modules as well as DDR-SDRAM products. HCD's highly reliable Land Grid Array (LGA) technology, SuperButton(TM), provides a minimum inductance, low-contact force, high pincount connector solution at low cost. For more information on HCD's innovative high-density SuperButton connector technology and, high-performance modules, please contact Angela Martin, at High Connection Density, Inc. 408/743-9700 Ext. 306

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